IPC ASSOCIATION ELECTRONIC	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved u international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Typ Distribute								erials and N	ials and Mfg Information					
Supplier	• Information														
Company name*			Company unique ID			ı	Unique ID Authority				Respon	Response Date*			
onsemi											2024-0	2024-05-07			
Contact N	ame	Title - Contact]	Phone - Contact*				Email	Email - Contact*				
Product-E	Env-Stewards		Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
Authorize	d Representative*	Title - Representative]	Phone - Representative*				Email	Email - Representative*				
Product-E	Env-Stewards		Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr		m Number Mfr Item Name				Effective Dat	te Versi	on 1	Manufacturing Site		Weight*	UOM	Unit Type	
		NVATS5A106PLZT4 PCH 4		PCH 4.5V DRIVE SERIES			2024-05-07		•	CNG		262.59	mg	Each	
Aanufa	cturing Process Information	ation													
	Terminal Plating / Grid Array M	Ferminal Base Alloy J-STD-020 MSL			SL Rating	ing Peak Process Body Temperature Max Time at Pea				ak Tempera	ture Nu	mber of Reflow Cy	cles		
contains Bi			CU Alloy 1			260	260 C		30	seco	nds 3				
omments															
vel 1 - m	aximum time at peak tempera	ture during sol	dering is 10-3	0 seconds											
or more i	nformation regarding materia	l composition	please refer to	page 3		•	•		•	-	•	•		-	

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.66	mg	Supplier	Silicon (Si)	7440-21-3		1.66	mg
Die Attach	2.85		Supplier	Silver (Ag)	7440-22-4		0.0556	mg
			A	Lead (Pb)	7439-92-1	7a	2.6519	mg
			Supplier	Tin (Sn)	7440-31-5		0.1425	mg
Lead Frame	148.04		Supplier	Tin (Sn)	7440-31-5		0.2221	mg
			Supplier	Copper (Cu)	7440-50-8		147.8179	mg
Mold Compound-Black	106.73	mg		Phenolic Resin	proprietary data		2.6683	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		8.8052	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5336	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		94.1892	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.5336	mg
Plating	3.31	mg	В	Bismuth (Bi)	7440-69-9		0.0199	mg
			Supplier	Tin (Sn)	7440-31-5		3.2901	mg